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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

PRELIMINARY AMENDMENT ACCOMPANYING SUBMISSION OF MISSING PARTS

APPLICANT: Akira Yoshizawa, et al. ATTY. DOCKET NO. 09792909-5237

SERIAL NO.

DATE FILED:

INVENTION: "SEMICONDUCTOR DEVICE USING INTERPOSER SUBSTRATE AND MANUFACTURING METHOD THEREFOR"

Assistant Commissioner of Patents  
Washington, D.C. 20231

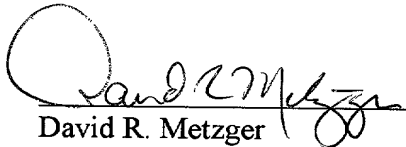
S I R:

Applicants submit this Preliminary Amendment for consideration in the above-identified patent application:

IN THE SPECIFICATION

At page 10, line 16, change "Figs. 4A to 4F" to --Figs. 4A to 4J--.

Respectfully submitted,

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FIG. 4A

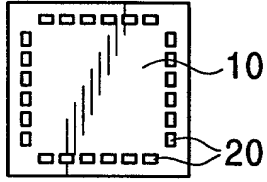


FIG. 4B

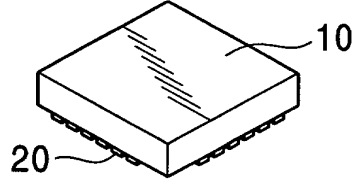


FIG. 4C

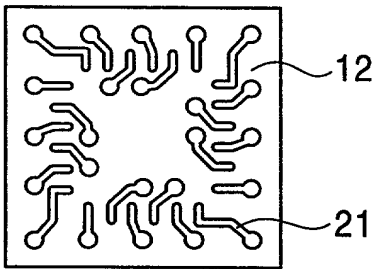


FIG. 4D

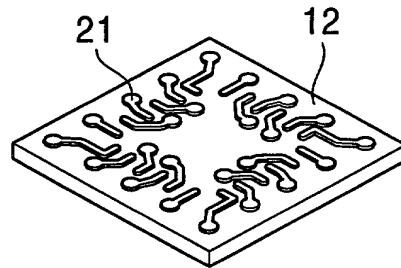


FIG. 4E

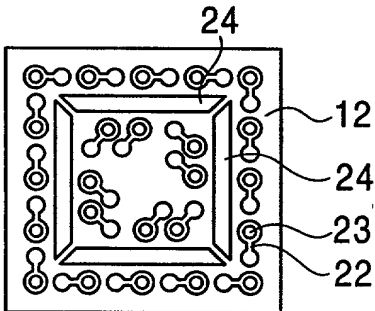
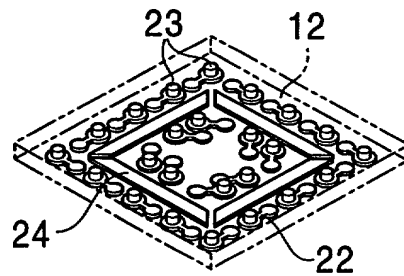


FIG. 4F



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FIG. 4G

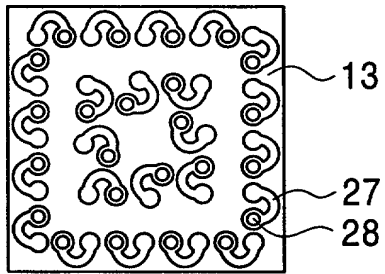


FIG. 4H

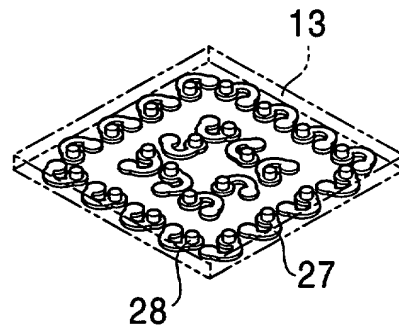


FIG. 4I

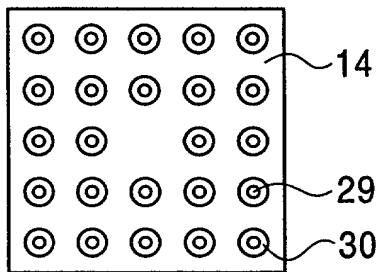
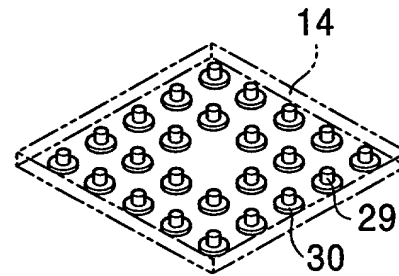


FIG. 4J



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